Quad 2-Input NAND Gate

With 5 V-Tolerant Inputs

The MC74LVX00 is an advanced high speed CMOS 2-input NAND gate. The inputs tolerate voltages up to 7.0 V, allowing the interface of 5.0 V systems to 3.0 V systems.

Features

- High Speed: $t_{PD} = 4.1 \text{ ns}$ (Typ) at $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation: $I_{CC} = 2 \mu A \text{ (Max)}$ at $T_A = 25 \text{°C}$
- · Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: V_{OLP} = 0.5 V (Max)
- · Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance:

Human Body Model > 2000 V; Machine Model > 200 V

• These Devices are Pb-Free and are RoHS Compliant

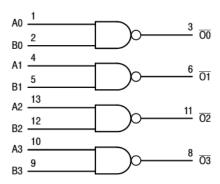


Figure 1. Logic Diagram

PIN NAMES

| Pins | Function |
|--------|-------------|
| An, Bn | Data Inputs |
| On | Outputs |

FUNCTION TABLE

| Inp | uts | Outputs |
|-----|-----|---------|
| An | Bn | On |
| L | L | Н |
| L | Н | Н |
| Н | L | Н |
| Н | Н | L |



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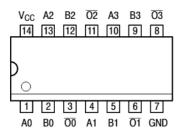
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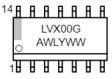
SOIC-14 NB D SUFFIX CASE 751A TSSOP-14 DT SUFFIX CASE 948G

PIN ASSIGNMENT



14-Lead (Top View)

MARKING DIAGRAMS



SOIC-14 NB



TSSOP-14

LVX00 = Specific Device Code A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|------------------|---|------------------------------|------|
| V _{CC} | DC Supply Voltage | -0.5 to +7.0 | V |
| V _{IN} | DC Input Voltage | -0.5 to +7.0 | V |
| V _{out} | DC Output Voltage | -0.5 to V _{CC} +0.5 | V |
| I _{IK} | Input Diode Current | -20 | mA |
| I _{OK} | Output Diode Current | ±20 | mA |
| I _{out} | DC Output Current, per Pin | ±25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ±50 | mA |
| P _D | Power Dissipation | 180 | mW |
| T _{stg} | Storage Temperature | -65 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|------------------|--|-----|-----------------|------|
| V _{CC} | DC Supply Voltage | 2.0 | 3.6 | V |
| V _{IN} | DC Input Voltage | 0 | 5.5 | V |
| V _{out} | DC Output Voltage | 0 | V _{CC} | V |
| T _A | Operating Temperature, All Package Types | -40 | +85 | °C |
| Δt/ΔV | Input Rise and Fall Time | 0 | 100 | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

| | | | V _{CC} | | T _A = 25°C | | T _A = -40 | to 85°C | |
|-----------------|--|---|-------------------|--------------------|-----------------------|--------------------|----------------------|--------------------|------|
| Symbol | Parameter | Test Conditions | V | Min | Тур | Max | Min | Max | Unit |
| V _{IH} | High-Level Input Voltage | | 2.0 3.0 3.6 | 1.5 2.0 2.4 | | | 1.5 2.0 2.4 | | V |
| V _{IL} | Low-Level Input Voltage | | 2.0 3.0 3.6 | | | 0.5 0.8 0.8 | | 0.5 0.8 0.8 | V |
| V _{OH} | High-Level Output Voltage (V _{IN} = V _{IH} or V _{IL}) | I _{OH} = -50 μA I _{OH} = -50 μA I _{OH} = -4 mA | 2.0 3.0 3.0 | 1.9 2.9 2.58 | 2.0 3.0 | | 1.9 2.9 2.48 | | V |
| V _{OL} | Low-Level Output Voltage (V _{IN} = V _{IH} or V _{IL}) | I _{OL} = 50 μA I _{OL} = 50 μA I _{OL} = 4 mA | 2.0 3.0 3.0 | | 0.0 0.0 | 0.1 0.1 0.36 | | 0.1 0.1 0.44 | V |
| I _{in} | Input Leakage Current | V _{IN} = 5.5 V or GND | 3.6 | | | ±0.1 | | ±1.0 | μΑ |
| Icc | Quiescent Supply Current | V _{IN} = V _{CC} or GND | 3.6 | | | 2.0 | | 20.0 | μΑ |

AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0 \text{ ns}$)

| | | | | | T _A = 25°C | | T _A = -40 | to 85°C | |
|--|---------------------------------------|---|--|-----|-----------------------|--------------|----------------------|--------------|------|
| Symbol | Parameter | Test Condi | tions | Min | Тур | Max | Min | Max | Unit |
| t _{PLH} , t _{PHL} | Propagation Delay, Input to Output | V _{CC} = 2.7 V | $C_L = 15 pF$ $C_L = 50 pF$ | | 5.4 7.9 | 10.1 13.6 | 1.0 1.0 | 12.5 16.0 | ns |
| | | V _{CC} = 3.3 ±0.3 V | $C_L = 15 pF$ $C_L = 50 pF$ | | 4.1 6.6 | 6.2 9.7 | 1.0 1.0 | 7.5 11.0 | |
| toshl toslh | Output-to-Output Skew (Note 1) | V _{CC} = 2.7 V V _{CC} = 3.3 ±0.3 V | $C_L = 50 \text{ pF}$ $C_L = 50 \text{ pF}$ | | | 1.5 1.5 | | 1.5 1.5 | ns |

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

| | | T _A = 25°C | | T _A = -40 to 85°C | | | |
|-----------------|--|-----------------------|-----|------------------------------|-----|-----|------|
| Symbol | Parameter | Min | Тур | Max | Min | Max | Unit |
| Cin | Input Capacitance | | 4 | 10 | | 10 | pF |
| C _{PD} | Power Dissipation Capacitance (Note 2) | | 19 | | | | pF |

^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/4 (per gate). C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

NOISE CHARACTERISTICS (Input $t_f = t_f = 3.0$ ns, $C_L = 50$ pF, $V_{CC} = 3.3$ V, Measured in SOIC Package)

| | | T _A = | 25°C | |
|------------------|--|------------------|------|------|
| Symbol | Characteristic | Тур | Max | Unit |
| V _{OLP} | Quiet Output Maximum Dynamic V _{OL} | 0.3 | 0.5 | V |
| V _{OLV} | Quiet Output Minimum Dynamic V _{OL} | -0.3 | -0.5 | V |
| V _{IHD} | Minimum High Level Dynamic Input Voltage | | 2.0 | V |
| V _{ILD} | Maximum Low Level Dynamic Input Voltage | | 0.8 | V |

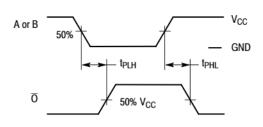
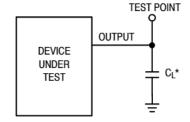


Figure 2. Switching Waveforms



*Includes all probe and jig capacitance

Figure 3. Test Circuit

ORDERING INFORMATION

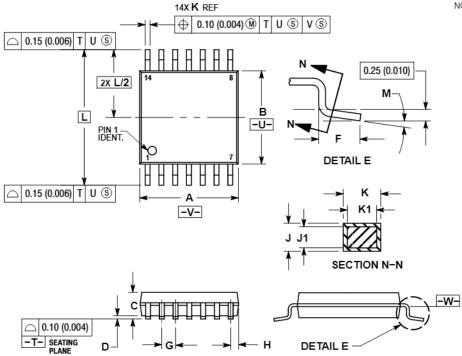
| Device | Package | Shipping [†] |
|----------------|-------------------------|-----------------------|
| MC74LVX00DR2G | SOIC-14 NB (Pb-Free) | 2500 Tape & Reel |
| MC74LVX00DTR2G | TSSOP-14* | 2500 Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}This package is inherently Pb-Free.

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G **ISSUE B**



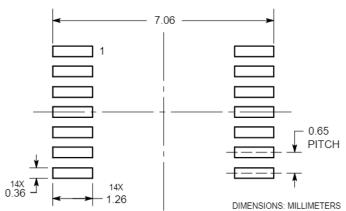
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER

 - 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14 5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
 NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL
 BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM
 MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE

 - 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

| | MILLIN | IETERS | INC | HES | |
|-----|--------|--------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 4.90 | 5.10 | 0.193 | 0.200 | |
| В | 4.30 | 4.50 | 0.169 | 0.177 | |
| С | | 1.20 | | 0.047 | |
| D | 0.05 | 0.15 | 0.002 | 0.006 | |
| F | 0.50 | 0.75 | 0.020 | 0.030 | |
| G | 0.65 | BSC | 0.026 | BSC | |
| Н | 0.50 | 0.60 | 0.020 | 0.024 | |
| J | 0.09 | 0.20 | 0.004 | 0.008 | |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 | |
| K | 0.19 | 0.30 | 0.007 | 0.012 | |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 | |
| L | 6.40 | BSC | 0.252 BSC | | |
| M | 0 ° | 8° | 0 ° | 8° | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

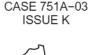
PACKAGE DIMENSIONS

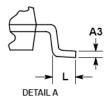
SOIC-14 NB В Н 13X **b** 0.25 M B (M)

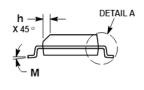
 \oplus

0.25 M C A S B S

C SEATING



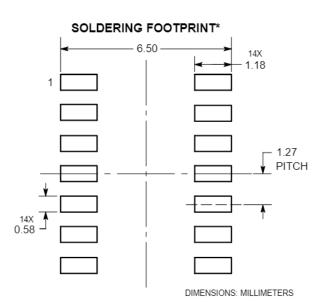




NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- 2. OMVACULING DIMINISTON INICIDIES DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

| | MILLIN | IETERS | INCHES | | |
|-----|----------|--------|--------|-------|--|
| DIM | MIN MAX | | MIN | MAX | |
| Α | 1.35 | 1.75 | 0.054 | 0.068 | |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 | |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 | |
| b | 0.35 | 0.49 | 0.014 | 0.019 | |
| D | 8.55 | 8.75 | 0.337 | 0.344 | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | |
| е | 1.27 BSC | | 0.050 | BSC | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | |
| h | 0.25 | 0.50 | 0.010 | 0.019 | |
| L | 0.40 | 1.25 | 0.016 | 0.049 | |
| М | 0 ° | 7° | 0° | 7° | |



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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